Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

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ENESA

MOS FIELD EFFECT TRANSISTOR

NP80N06MLG, NP80N06NLG, NP80N06PLG

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The NP80N06MLG, NP80N06NLG, and NP80N06PLG are N-channel MOS Field Effect Transistors designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
NP80N06MLG-S18-AY Note		Tube	TO-220 (MP-25K) typ. 1.9 g
NP80N06NLG-S18-AY Note		50 p/tube	TO-262 (MP-25SK) typ. 1.8 g
NP80N06PLG-E1B-AY Note	Pure Sn (Tin)	Таре	
NP80N06PLG-E2B-AY Note		1000 p/reel	TO-263 (MP-25ZP) typ. 1.5 g

Note Pb-free (This product does not contain Pb in the external electrode.)

FEATURES

- Logic level
- Built-in gate protection diode
- Super low on-state resistance
- NP80N06MLG, NP80N06NLG

 $R_{DS(on)1}$ = 8.6 m Ω MAX. (V_{GS} = 10 V, I_D = 40 A)

 $R_{DS(on)2}$ = 13.3 m Ω MAX. (VGS = 4.5 V, ID = 35 A)

- NP80N06PLG

 $R_{DS(on)1}$ = 8.3 m Ω MAX. (V_{GS} = 10 V, I_D = 40 A)

 $R_{DS(on)2}$ = 13 m Ω MAX. (VGs = 4.5 V, ID = 35 A)

• High current rating

ID(DC) = ±80 A

Low input capacitance

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Ciss = 4600 pF TYP.
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• Designed for automotive application and AEC-Q101 qualified

(TO-220)





(TO-263)



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Document No. D19798EJ1V0DS00 (1st edition) Date Published May 2009 NS Printed in Japan

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Drain to Source Voltage (VGS = 0 V)	VDSS	60	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	D(DC)	±80	А
Drain Current (pulse) Note1	D(pulse)	±180	А
Total Power Dissipation (Tc = 25° C)	PT1	115	W
Total Power Dissipation (T _A = 25°C)	P _{T2}	1.8	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Repetitive Avalanche Current Note2	lar	32	А
Repetitive Avalanche Energy Note2	Ear	102	mJ

Notes 1. $PW \leq$ 10 $\mu s, \, Duty \, Cycle \leq$ 1%

2. $T_{ch} \le 150^{\circ}C$, R_G = 25 Ω

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.30	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

ELECTRICAL CHARACTERISTICS (TA = 25°	'C)
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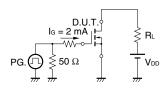
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 60 V, V _{GS} = 0 V			1	μA
Gate Leakage Current	lgss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μA
Gate to Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.4		2.5	V
Forward Transfer Admittance Note	y _{fs}	Vds = 5 V, Id = 35 A	25	59		S
Drain to Source On-state Resistance Note	RDS(on)1	V _{GS} = 10 V, I _D = 40 A NP80N06MLG, NP80N06NLG		6.7	8.6	mΩ
		V _{GS} = 10 V, I _D = 40 A NP80N06PLG		6.2	8.3	mΩ
	RDS(on)2	V _{GS} = 4.5 V, I _D = 35 A NP80N06MLG, NP80N06NLG		8.4	13.3	mΩ
		V _{GS} = 4.5 V, I _D = 35 A NP80N06PLG		7.6	13	mΩ
Input Capacitance	Ciss	V _{DS} = 25 V,		4600	6900	pF
Output Capacitance	Coss	V _{GS} = 0 V,		370	560	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		220	400	pF
Turn-on Delay Time	td(on)	V _{DD} = 30 V, I _D = 40 A,		17	37	ns
Rise Time	tr	V _{GS} = 10 V,		13	33	ns
Turn-off Delay Time	td(off)	R _G = 0 Ω		70	140	ns
Fall Time	tr			7	18	ns
Total Gate Charge	QG	V _{DD} = 48 V,		85	128	nC
Gate to Source Charge	Q _{GS}	V _{GS} = 10 V,		14		nC
Gate to Drain Charge	Qgd	I⊳ = 80 A		25		nC
Body Diode Forward Voltage Note	VF(S-D)	IF = 80 A, VGS = 0 V		0.96	1.5	V
Reverse Recovery Time	trr	IF = 80 A, VGS = 0 V,		41		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>μ</i> s		56		nC

Note Pulsed test

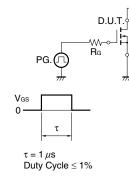
TEST CIRCUIT 1 AVALANCHE CAPABILITY

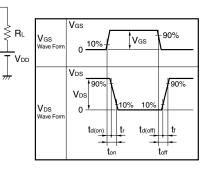
$V_{GS} = 20 \rightarrow 0 V$ $PG. \qquad PG. \qquad PG. \qquad PG. \qquad V_{DD}$ $V_{DD} \qquad V_{DD}$

TEST CIRCUIT 3 GATE CHARGE

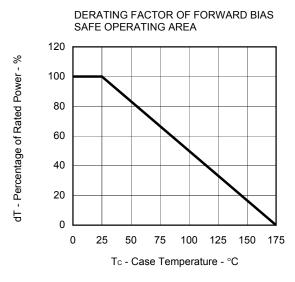


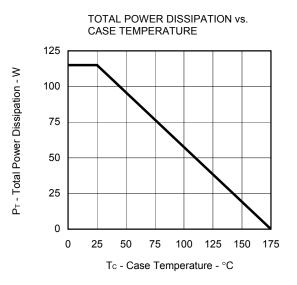
TEST CIRCUIT 2 SWITCHING TIME



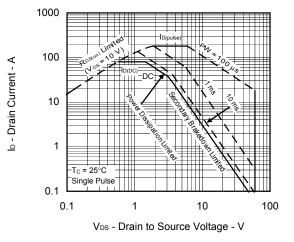


TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}C$)

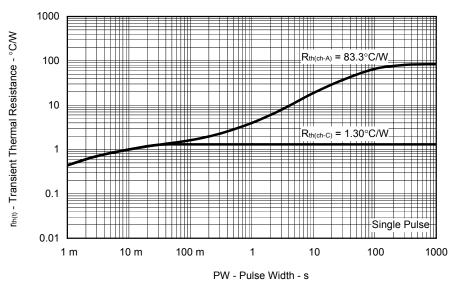




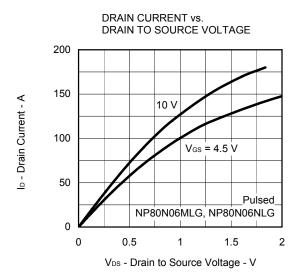




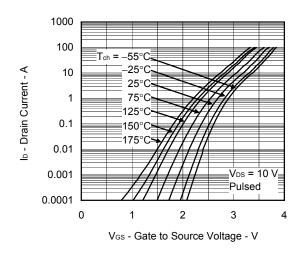
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

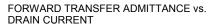


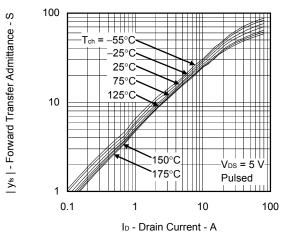
Data Sheet D19798EJ1V0DS

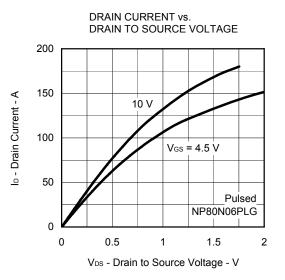


FORWARD TRANSFER CHARACTERISTICS

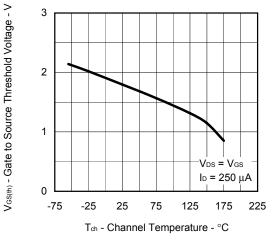


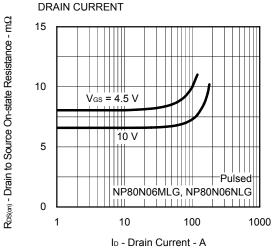






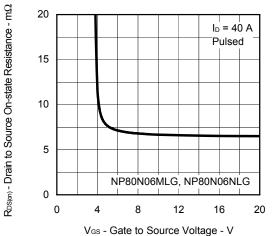
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

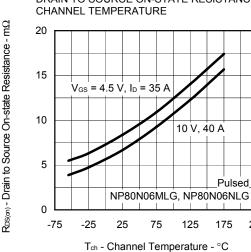




DRAIN TO SOURCE ON-STATE RESISTANCE vs.

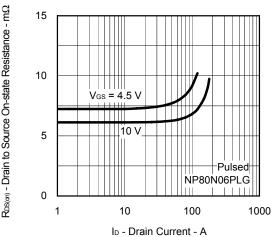




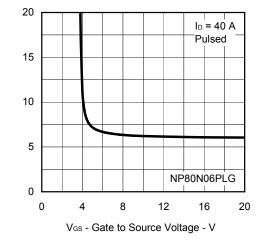


DRAIN TO SOURCE ON-STATE RESISTANCE vs.

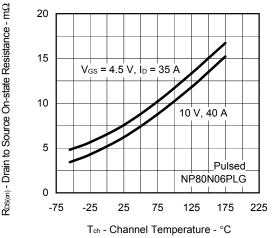
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

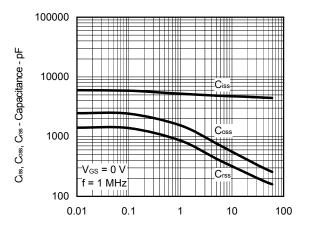


225

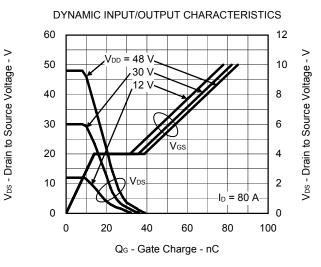
 $R_{DS(on)}$ - Drain to Source On-state Resistance - m Ω

NEC

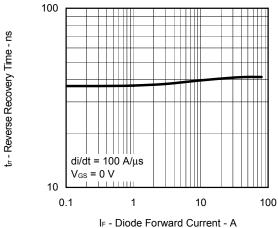
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



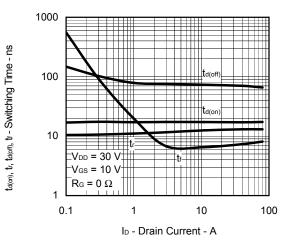
VDS - Drain to Source Voltage - V



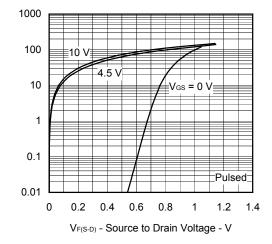




SWITCHING CHARACTERISTICS

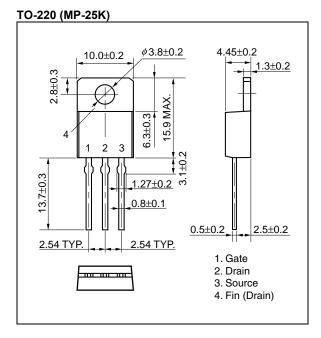


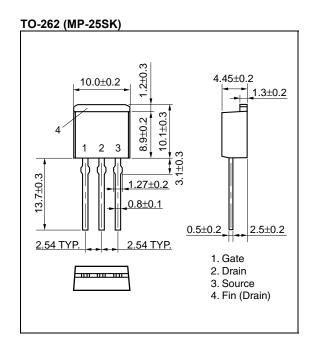
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



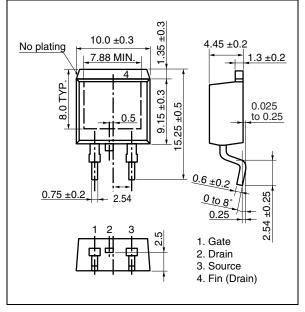
IF - Diode Forward Current - A

PACKAGE DRAWINGS (Unit: mm)

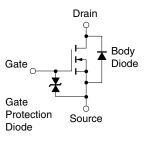




TO-263 (MP-25ZP)



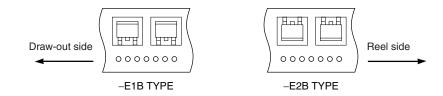
EQUIVALENT CIRCUIT



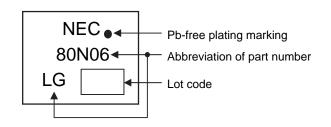
Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

TAPE INFORMATION (NP80N06PLG)

There are two types (-E1B, -E2B) of taping depending on the direction of the device.



MARKING INFORMATION



RECOMMENDED SOLDERING CONDITIONS

These products should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, please contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (http://www.necel.com/pkg/en/mount/index.html)

Soldering Method	Soldering Conditions	Recommended Condition Symbol
Infrared reflow NP80N06PLG	Maximum temperature (Package's surface temperature): 260°C or below Time at maximum temperature: 10 seconds or less Time of temperature higher than 220°C: 60 seconds or less Preheating time at 160 to 180°C: 60 to 120 seconds Maximum number of reflow processes: 3 times Maximum chlorine content of rosin flux (percentage mass): 0.2% or less	IR60-00-3
Wave soldering NP80N06MLG, NP80N06NLG	Maximum temperature (Solder temperature): 260°C or below Time: 10 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	THDWS
Partial heating NP80N06MLG, NP80N06NLG, NP80N06PLG	Maximum temperature (Pin temperature): 350°C or below Time (per side of the device): 3 seconds or less Maximum chlorine content of rosin flux: 0.2% (wt.) or less	P350

Caution Do not use different soldering methods together (except for partial heating).

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- "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
- "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

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